

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:  
Maloney, et al.

Serial No.  
Filed:

to be assigned  
herewith

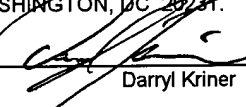
Atty. Docket No.: A-68359-1/RMA

**Apparatus And Method For Chemical-  
Mechanical Polishing (CMP) Head Having  
Direct Pneumatic Wafer Polishing Pressure**

"EXPRESS MAIL" MAILING LABEL  
NUMBER EL 758 643 060 US

DATE OF DEPOSIT: December 21, 2001  
I HEREBY CERTIFY THAT THIS PAPER OR FEE IS BEING  
DEPOSITED WITH THE UNITED STATES POSTAL SERVICE  
"EXPRESS MAIL POST OFFICE TO ADDRESSEE" SERVICE  
UNDER 37 CFR 1.10 ON THE DATE INDICATED ABOVE  
AND IS ADDRESSED TO: BOX PATENT APPLICATION FEE,  
ASSISTANT COMMISSIONER FOR PATENTS,  
WASHINGTON, DC 20231.

By

  
Darryl Kriner

4/B  
Re  
OK  
E. J. Kriner  
5/7/02

**PRELIMINARY AMENDMENT**

Assistant Commissioner for Patents  
Washington D.C. 20231  
Box Amendment

Sir:

Please amend the application as follows:

**IN THE CLAIMS**

Please add the following claims:

— 9. (New) A workpiece tooling head for polishing or planarizing a workpiece on a polishing pad,  
said polishing head comprising:

a retaining ring having an interior cylindrical surface and defining an interior cylindrical pocket sized  
to carry said workpiece and to laterally restrain movement of said workpiece when said workpiece is moved  
relative to said polishing pad while being polished against said polishing pad, said retaining ring having a lower  
surface that is pressed against said polishing pad by a first pressurized fluid to define a first pressure zone  
of said retaining ring against said polishing pad during polishing of said workpiece; and

10027935 122001

B